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(12) **United States Design Patent**
Mueller

(10) **Patent No.:** **US D660,810 S**
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(54) **HEAT SPREADER WITH FINS FOR A
COMPUTER MEMORY MODULE**

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(US)

(**) Term: **14 Years**

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(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.** **D13/179**

(58) **Field of Classification Search** D13/179;
165/80.3, 104.26, 104.33, 122, 151, 185;
257/706, 707, 718-722; 361/695, 697, 700,
361/702, 704, 709, 710, 711, 719

See application file for complete search history.

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Primary Examiner — Selina Sikder

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(57) **CLAIM**

The ornamental design for a heat spreader with fins for a computer memory module, as shown and described.

DESCRIPTION

FIG. 1 is a front right side perspective view of a first embodiment of a heat spreader with fins for a computer memory module showing our design;

FIG. 2 is a front view of the first embodiment of the heat spreader with fins for a computer memory module;

FIG. 3 is a rear view of the first embodiment of the heat spreader with fins for a computer memory module;

FIG. 4 is a top side view of the first embodiment of the heat spreader with fins for a computer memory module;

FIG. 5 is a bottom side view of the first embodiment of the heat spreader with fins for a computer memory module;

FIG. 6 is a right side view of the first embodiment of the heat spreader with fins for a computer memory module;

FIG. 7 is a left side view of the first embodiment of the heat spreader with fins for a computer memory module;

FIG. 8 is a front right side perspective view of a second embodiment of the heat spreader with fins for a computer memory module;

FIG. 9 is a front view of the second embodiment of the heat spreader with fins for a computer memory module;

FIG. 10 is a rear view of the second embodiment of the heat spreader with fins for a computer memory module;

FIG. 11 is a top side view of the second embodiment of the heat spreader with fins for a computer memory module;

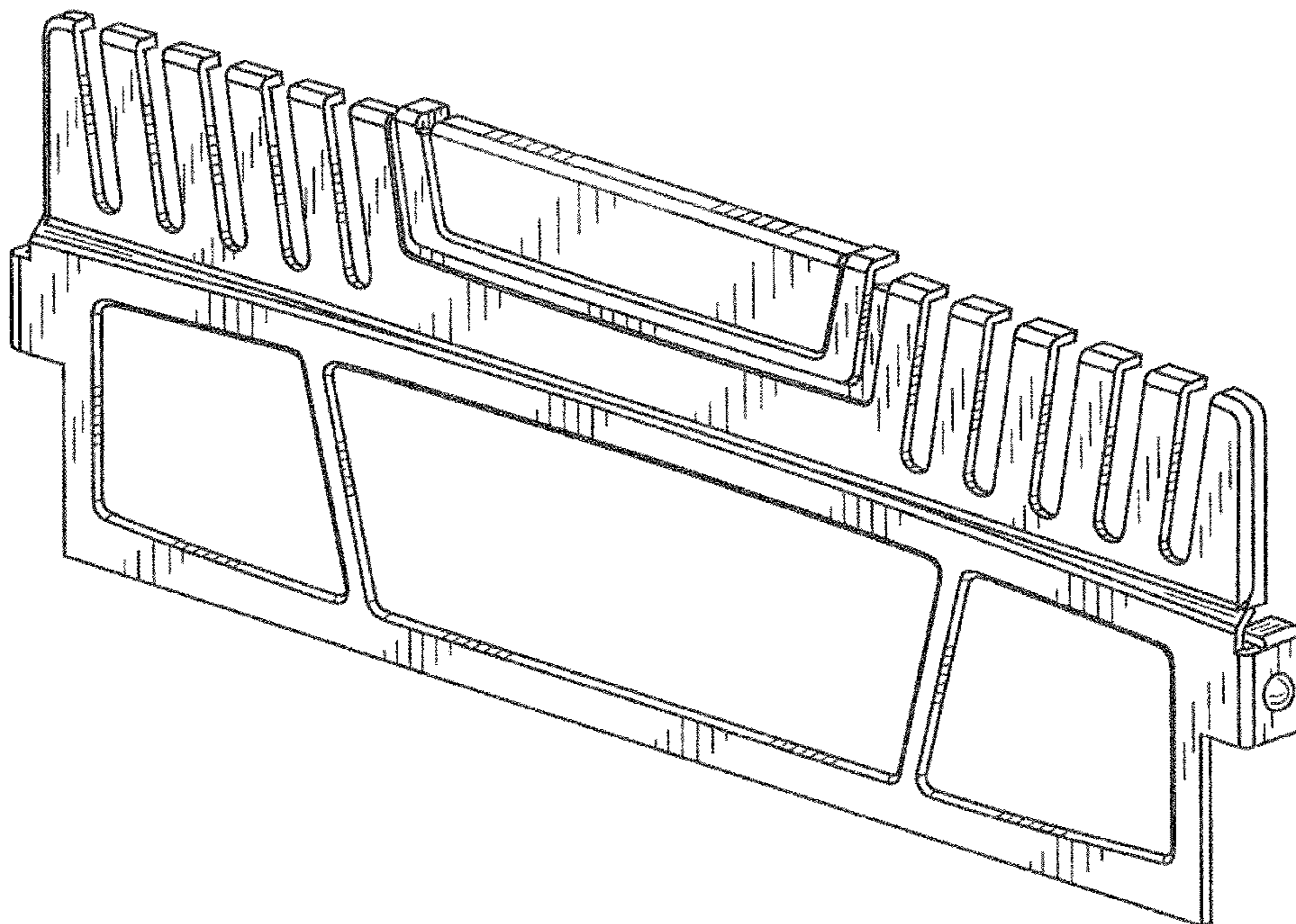
FIG. 12 is a bottom side view of the second embodiment of the heat spreader with fins for a computer memory module;

FIG. 13 is a right side view of the second embodiment of the heat spreader with fins for a computer memory module; and,

FIG. 14 is a left side view of the second embodiment of the heat spreader with fins for a computer memory module.

The shade lines in the figures show contour and not surface ornamentation.

1 Claim, 10 Drawing Sheets



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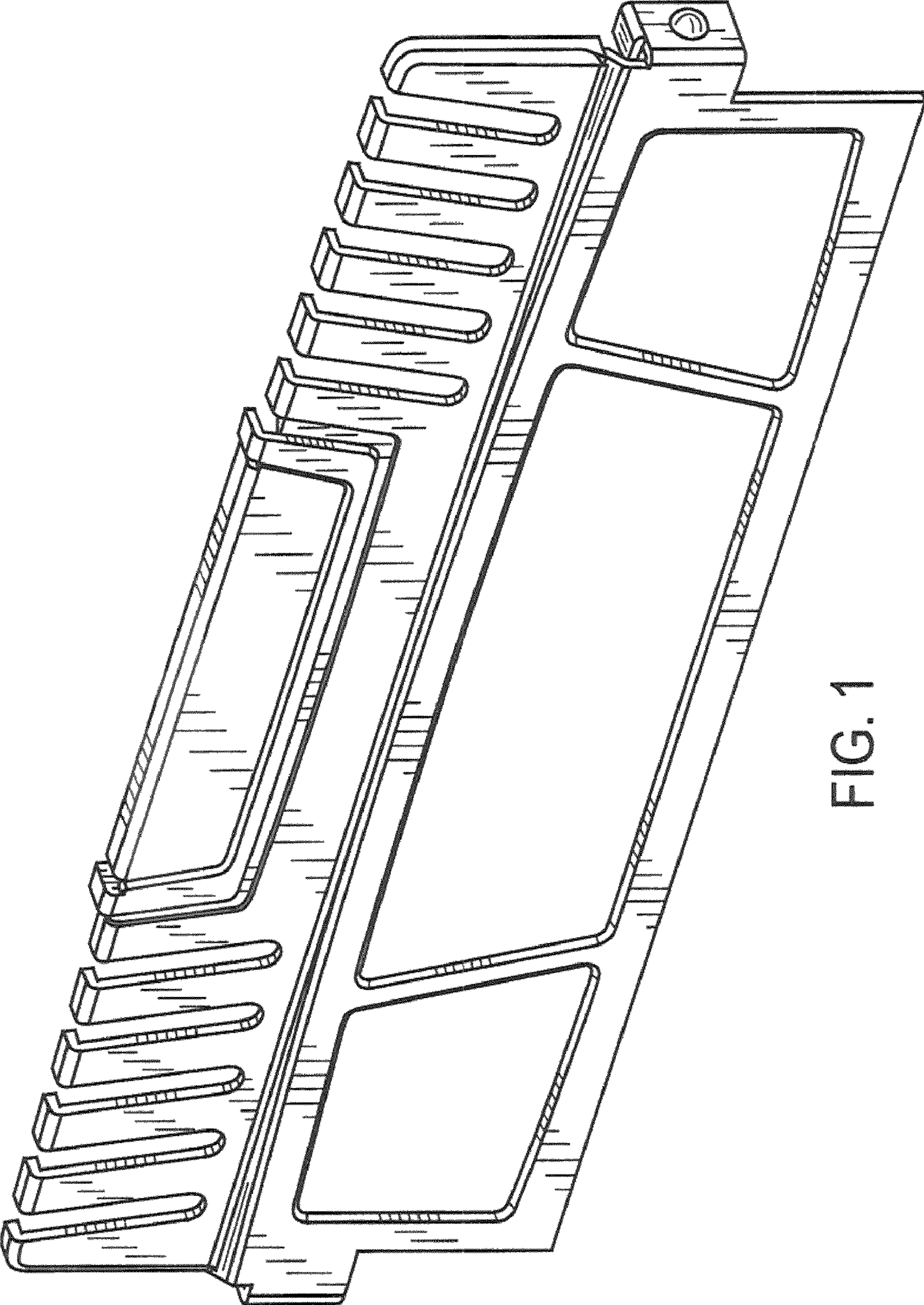


FIG. 1

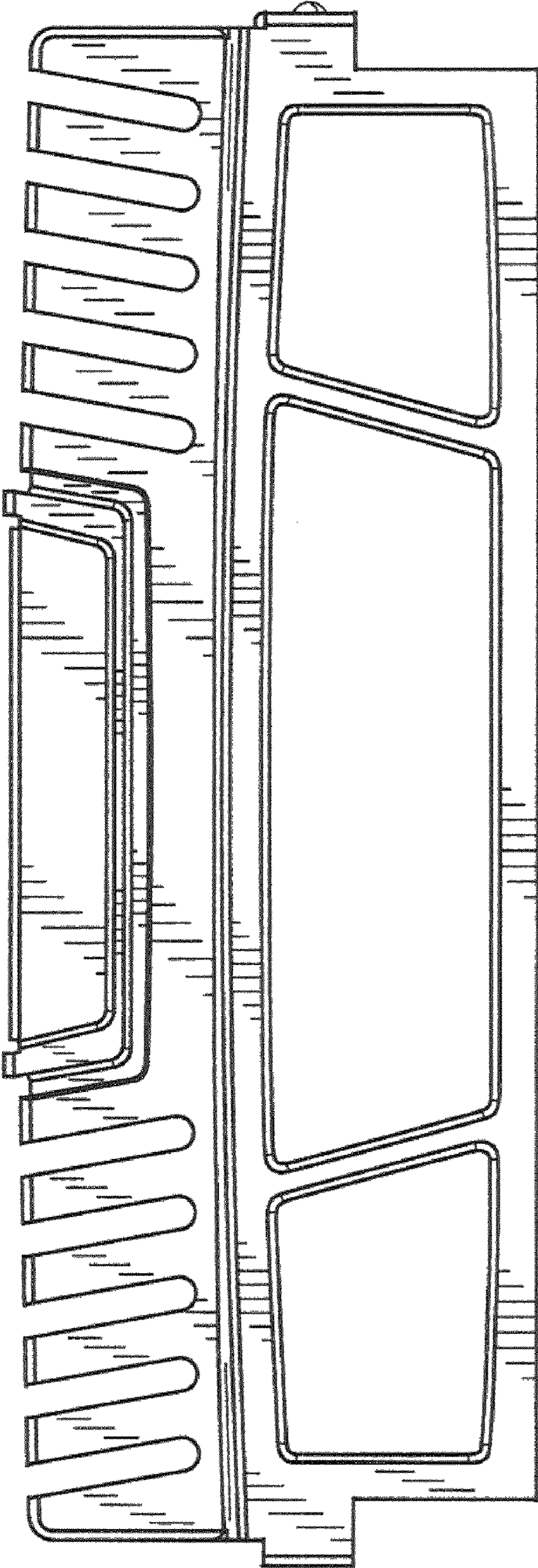


FIG. 2

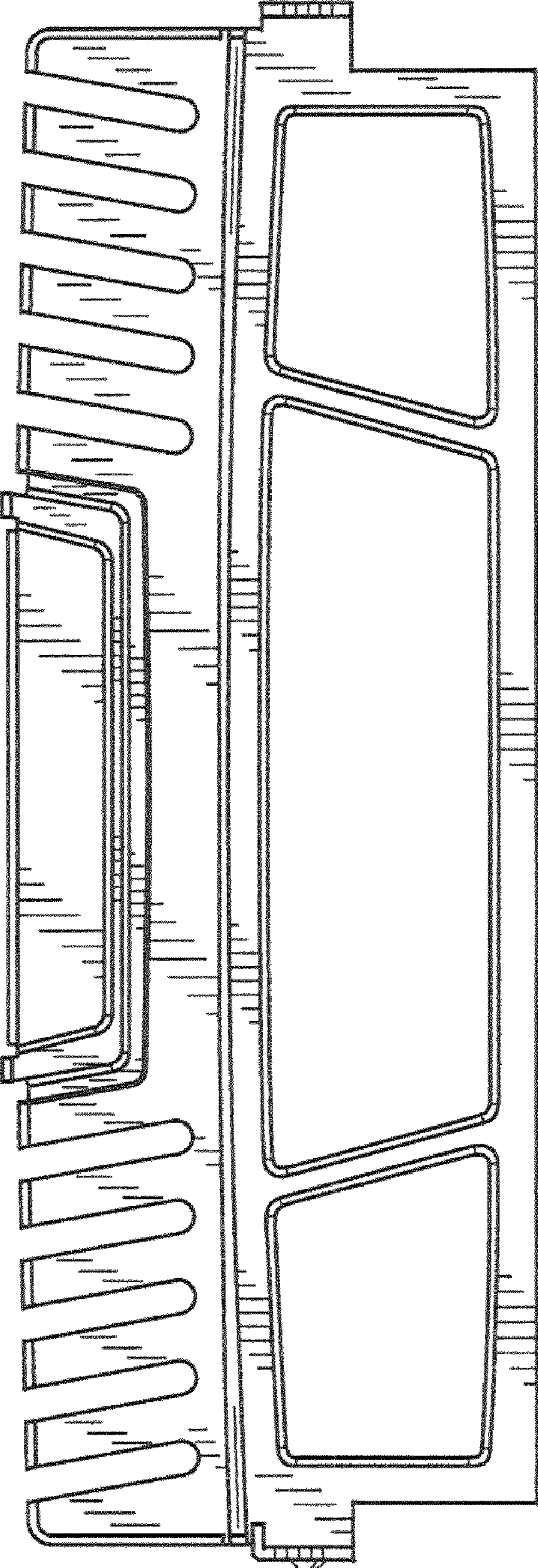


FIG. 3

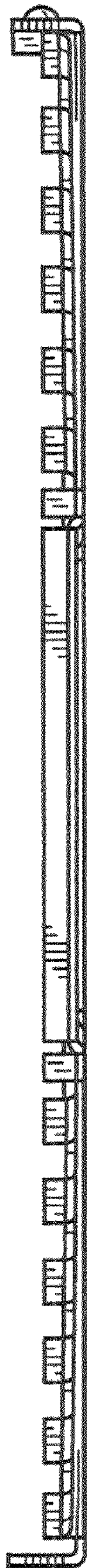


FIG. 4



FIG. 5

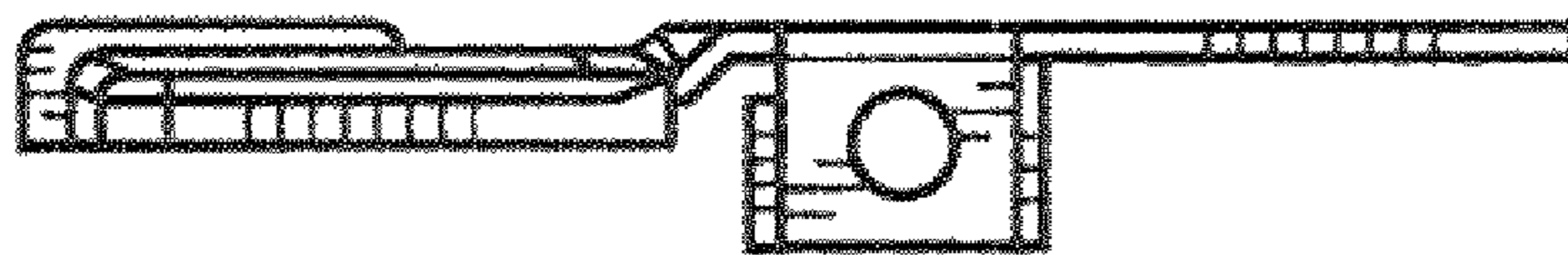


FIG. 7



FIG. 6

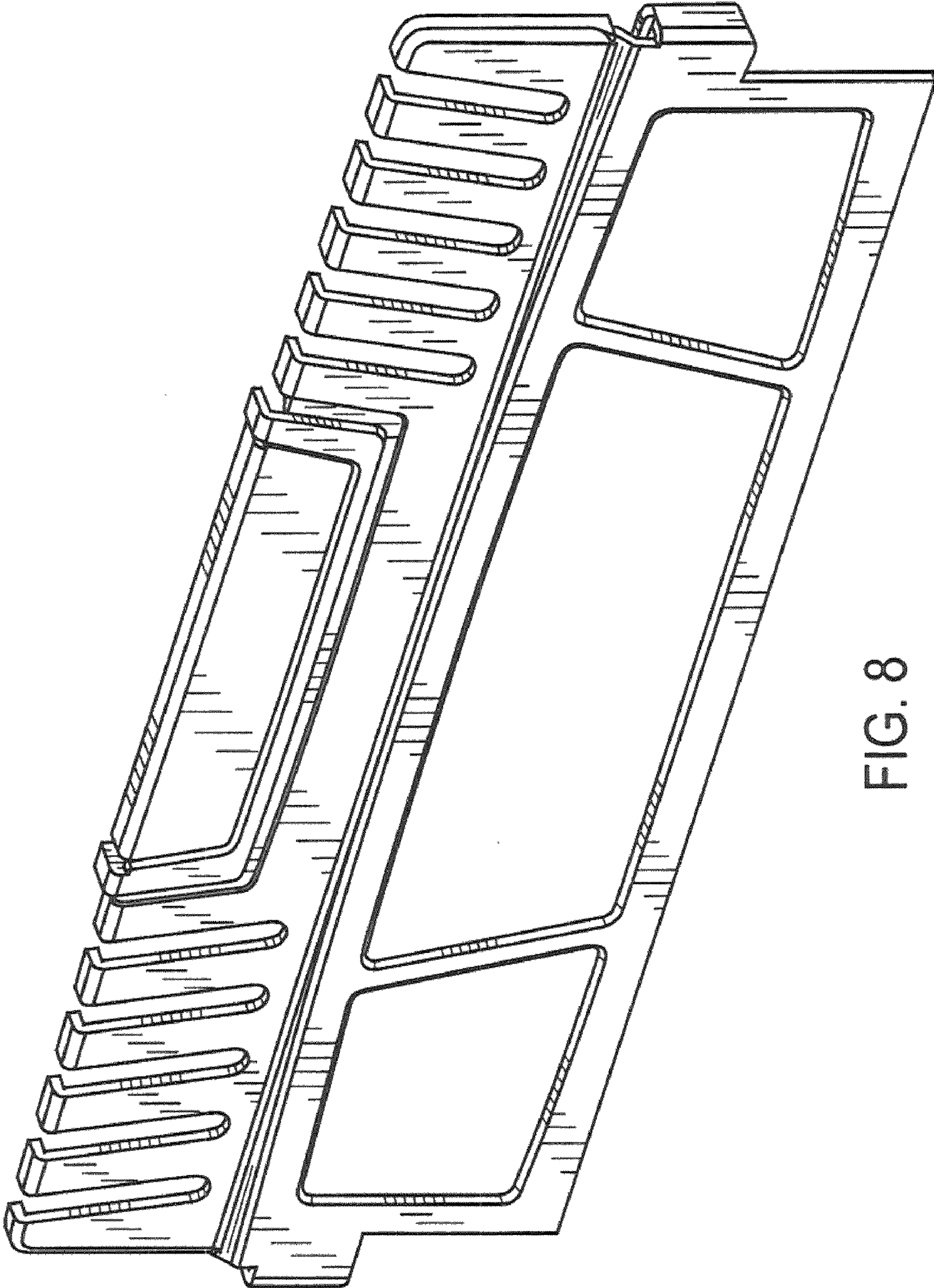


FIG. 8

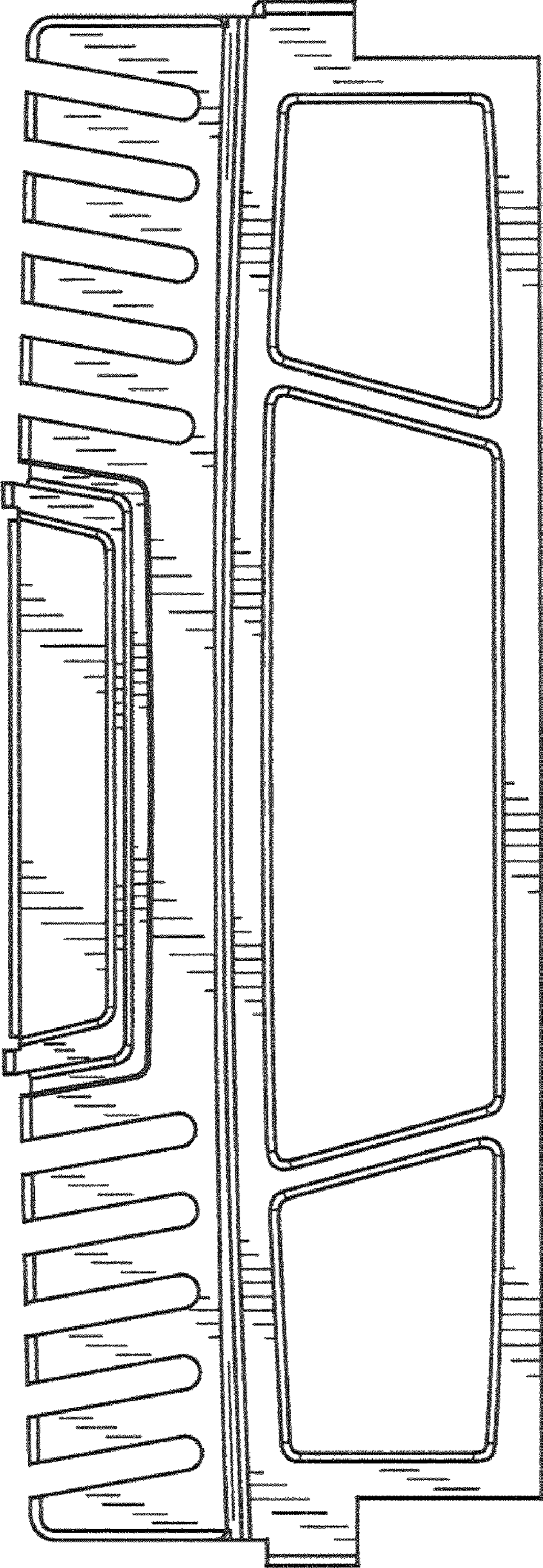


FIG. 9

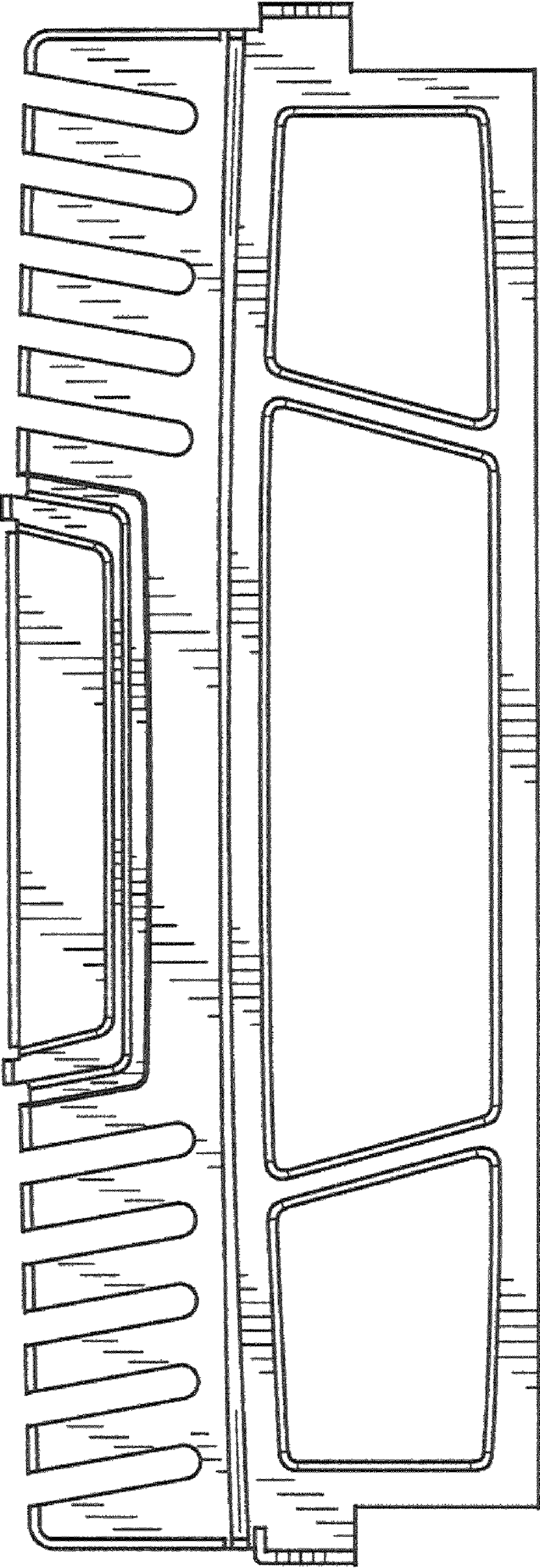


FIG. 10

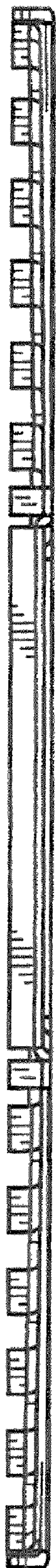


FIG. 11



FIG. 12



FIG. 14



FIG. 13